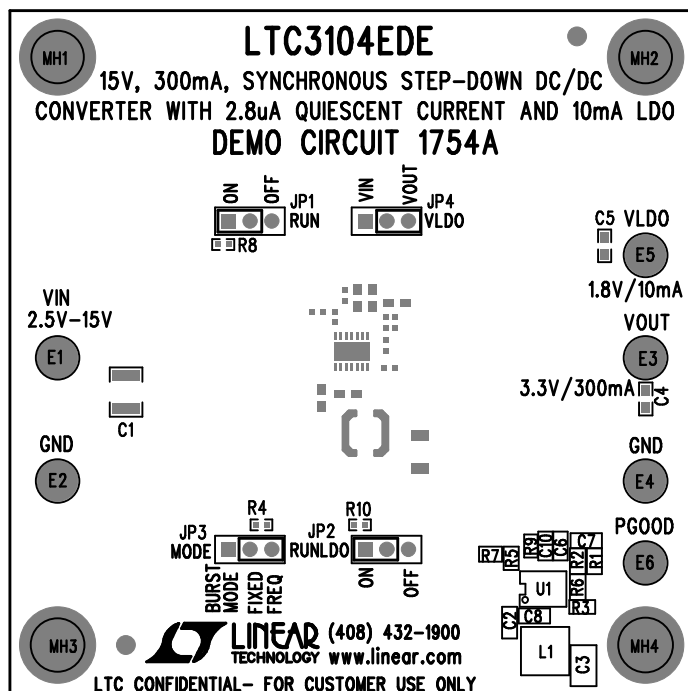
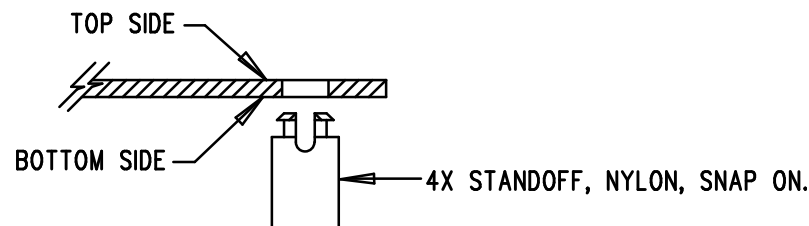



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	JIM N.	08-10-11



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS MH1-MH4 AS SHOWN BELOW:



APPROVALS		 LINEAR TECHNOLOGY 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY		
PCB DES.	LT			
APP ENG.	JIM N.	TITLE: TOP ASSEMBLY DRAWING		
		15V, 300mA, SYNCHRONOUS STEP-DOWN DC/DC CONVERTER WITH 2.8uA QUIESCENT CURRENT AND 10mA LDO		
		SIZE	IC NO. LTC3104EDE	REV.
		N/A	DEMO CIRCUIT 1754A	2
SCALE = NONE		FILENAME: DC1754A-2.PCB		SHT 1 OF 2